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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	10MHz
Connectivity	I²C, SPI
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	22
Program Memory Size	3.5KB (2K x 14)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	128 x 8
Voltage - Supply (Vcc/Vdd)	4V ~ 6V
Data Converters	A/D 5x8b
Oscillator Type	External
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	28-SSOP (0.209", 5.30mm Width)
Supplier Device Package	28-SSOP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16c72-10i-ss

TABLE 1-1 PIC16C72/CR72 PINOUT DESCRIPTION

Pin Name	Pin#	I/O/P Type	Buffer Type	Description
OSC1/CLKIN	9	I	ST/CMOS(3)	Oscillator crystal input/external clock source input.
OSC2/CLKOUT	10	O	—	Oscillator crystal output. Connects to crystal or resonator in crystal oscillator mode. In RC mode, the OSC2 pin outputs CLKOUT which has 1/4 the frequency of OSC1, and denotes the instruction cycle rate.
$\overline{MCLR}$/VPP	1	I/P	ST	Master clear (reset) input or programming voltage input. This pin is an active low reset to the device.
				PORTA is a bi-directional I/O port.
RA0/AN0	2	I/O	TTL	RA0 can also be analog input0.
RA1/AN1	3	I/O	TTL	RA1 can also be analog input1.
RA2/AN2	4	I/O	TTL	RA2 can also be analog input2.
RA3/AN3/VREF	5	I/O	TTL	RA3 can also be analog input3 or analog reference voltage
RA4/T0CKI	6	I/O	ST	RA4 can also be the clock input to the Timer0 module. Output is open drain type.
RA5/$\overline{SS}$/AN4	7	I/O	TTL	RA5 can also be analog input4 or the slave select for the synchronous serial port.
				PORTB is a bi-directional I/O port. PORTB can be software programmed for internal weak pull-up on all inputs.
RB0/INT	21	I/O	TTL/ST(1)	RB0 can also be the external interrupt pin.
RB1	22	I/O	TTL	
RB2	23	I/O	TTL	
RB3	24	I/O	TTL	
RB4	25	I/O	TTL	Interrupt on change pin.
RB5	26	I/O	TTL	Interrupt on change pin.
RB6	27	I/O	TTL/ST(2)	Interrupt on change pin. Serial programming clock.
RB7	28	I/O	TTL/ST(2)	Interrupt on change pin. Serial programming data.
				PORTC is a bi-directional I/O port.
RC0/T1OSO/T1CKI	11	I/O	ST	RC0 can also be the Timer1 oscillator output or Timer1 clock input.
RC1/T1OSI	12	I/O	ST	RC1 can also be the Timer1 oscillator input.
RC2/CCP1	13	I/O	ST	RC2 can also be the Capture1 input/Compare1 output/PWM1 output.
RC3/SCK/SCL	14	I/O	ST	RC3 can also be the synchronous serial clock input/output for both SPI and I^2C modes.
RC4/SDI/SDA	15	I/O	ST	RC4 can also be the SPI Data In (SPI mode) or data I/O (I^2C mode).
RC5/SDO	16	I/O	ST	RC5 can also be the SPI Data Out (SPI mode).
RC6	17	I/O	ST	
RC7	18	I/O	ST	
VSS	8, 19	P	—	Ground reference for logic and I/O pins.
VDD	20	P	—	Positive supply for logic and I/O pins.

Legend: I = input O = output I/O = input/output P = power
— = Not used TTL = TTL input ST = Schmitt Trigger input

Note 1: This buffer is a Schmitt Trigger input when configured as the external interrupt.
2: This buffer is a Schmitt Trigger input when used in serial programming mode.
3: This buffer is a Schmitt Trigger input when configured in RC oscillator mode and a CMOS input otherwise.

2.2.2.1 STATUS REGISTER

The STATUS register, shown in Figure 2-3, contains the arithmetic status of the ALU, the RESET status and the bank select bits for data memory.

The STATUS register can be the destination for any instruction, as with any other register. If the STATUS register is the destination for an instruction that affects the Z, DC or C bits, then the write to these three bits is disabled. These bits are set or cleared according to the device logic. Furthermore, the $\overline{TO}$ and $\overline{PD}$ bits are not writable. Therefore, the result of an instruction with the STATUS register as destination may be different than intended.

For example, `CLRF STATUS` will clear the upper-three bits and set the Z bit. This leaves the STATUS register as `000u u1uu` (where `u` = unchanged).

It is recommended, therefore, that only `BCF`, `BSF`, `SWAPF` and `MOVWF` instructions are used to alter the STATUS register because these instructions do not affect the Z, C or DC bits from the STATUS register. For other instructions, not affecting any status bits, see the "Instruction Set Summary."

Note 1: These devices do not use bits IRP and RP1 (STATUS<7:6>). Maintain these bits clear to ensure upward compatibility with future products.

Note 2: The C and DC bits operate as a $\overline{borrow}$ and $\overline{digit\ borrow}$ bit, respectively, in subtraction. See the `SUBLW` and `SUBWF` instructions for examples.

FIGURE 2-3: STATUS REGISTER (ADDRESS 03h, 83h)

R/W-0	R/W-0	R/W-0	R-1	R-1	R/W-x	R/W-x	R/W-x
IRP	RP1	RP0	$\overline{TO}$	$\overline{PD}$	Z	DC	C
bit7							bit0

R = Readable bit
W = Writable bit
U = Unimplemented bit, read as '0'
- n = Value at POR reset

bit 7: **IRP**: Register Bank Select bit (used for indirect addressing)
1 = Bank 2, 3 (100h - 1FFh)
0 = Bank 0, 1 (00h - FFh)

bit 6-5: **RP1:RP0**: Register Bank Select bits (used for direct addressing)
`11` = Bank 3 (180h - 1FFh)
`10` = Bank 2 (100h - 17Fh)
`01` = Bank 1 (80h - FFh)
`00` = Bank 0 (00h - 7Fh)
Each bank is 128 bytes. For devices with only Bank0 and Bank1, the IRP bit is reserved. Always maintain this bit clear.

bit 4: **$\overline{TO}$**: Time-out bit
1 = After power-up, `CLRWDT` instruction, or `SLEEP` instruction
0 = A WDT time-out occurred

bit 3: **$\overline{PD}$**: Power-down bit
1 = After power-up or by the `CLRWDT` instruction
0 = By execution of the `SLEEP` instruction

bit 2: **Z**: Zero bit
1 = The result of an arithmetic or logic operation is zero
0 = The result of an arithmetic or logic operation is not zero

bit 1: **DC**: Digit carry/$\overline{borrow}$ bit (`ADDWF`, `ADDLW`, `SUBLW`, `SUBWF` instructions) (for $\overline{borrow}$ the polarity is reversed)
1 = A carry-out from the 4th low order bit of the result occurred
0 = No carry-out from the 4th low order bit of the result

bit 0: **C**: Carry/$\overline{borrow}$ bit (`ADDWF`, `ADDLW`, `SUBLW`, `SUBWF` instructions)
1 = A carry-out from the most significant bit of the result occurred
0 = No carry-out from the most significant bit of the result occurred
Note: For $\overline{borrow}$ the polarity is reversed. A subtraction is executed by adding the two's complement of the second operand. For rotate (`RRF`, `RLF`) instructions, this bit is loaded with either the high or low order bit of the source register.

2.2.2.6 PCON REGISTER

The Power Control (PCON) register contains a flag bit to allow differentiation between a Power-on Reset (POR) to an external $\overline{MCLR}$ Reset or WDT Reset. Those devices with brown-out detection circuitry contain an additional bit to differentiate a Brown-out Reset condition from a Power-on Reset condition.

Note:	$\overline{BOR}$ is unknown on Power-on Reset. It must then be set by the user and checked on subsequent resets to see if $\overline{BOR}$ is clear, indicating a brown-out has occurred. The $\overline{BOR}$ status bit is a don't care and is not necessarily predictable if the brown-out circuit is disabled (by clearing the BODEN bit in the Configuration word).

FIGURE 2-8: PCON REGISTER (ADDRESS 8Eh)

U-0	U-0	U-0	U-0	U-0	U-0	R/W-0	R/W-q
—	—	—	—	—	—	$\overline{POR}$	$\overline{BOR}$
bit7							bit0

R = Readable bit
W = Writable bit
U = Unimplemented bit, read as '0'
- n = Value at POR reset

bit 7-2: **Unimplemented:** Read as '0'

bit 1: **$\overline{POR}$**: Power-on Reset Status bit
1 = No Power-on Reset occurred
0 = A Power-on Reset occurred (must be set in software after a Power-on Reset occurs)

bit 0: **$\overline{BOR}$**: Brown-out Reset Status bit
1 = No Brown-out Reset occurred
0 = A Brown-out Reset occurred (must be set in software after a Brown-out Reset occurs)

2.5 Indirect Addressing, INDF and FSR Registers

The INDF register is not a physical register. Addressing INDF actually addresses the register whose address is contained in the FSR register (FSR is a *pointer*). This is indirect addressing.

EXAMPLE 2-1: INDIRECT ADDRESSING

- Register file 05 contains the value 10h
- Register file 06 contains the value 0Ah
- Load the value 05 into the FSR register
- A read of the INDF register will return the value of 10h
- Increment the value of the FSR register by one (FSR = 06)
- A read of the INDR register now will return the value of 0Ah.

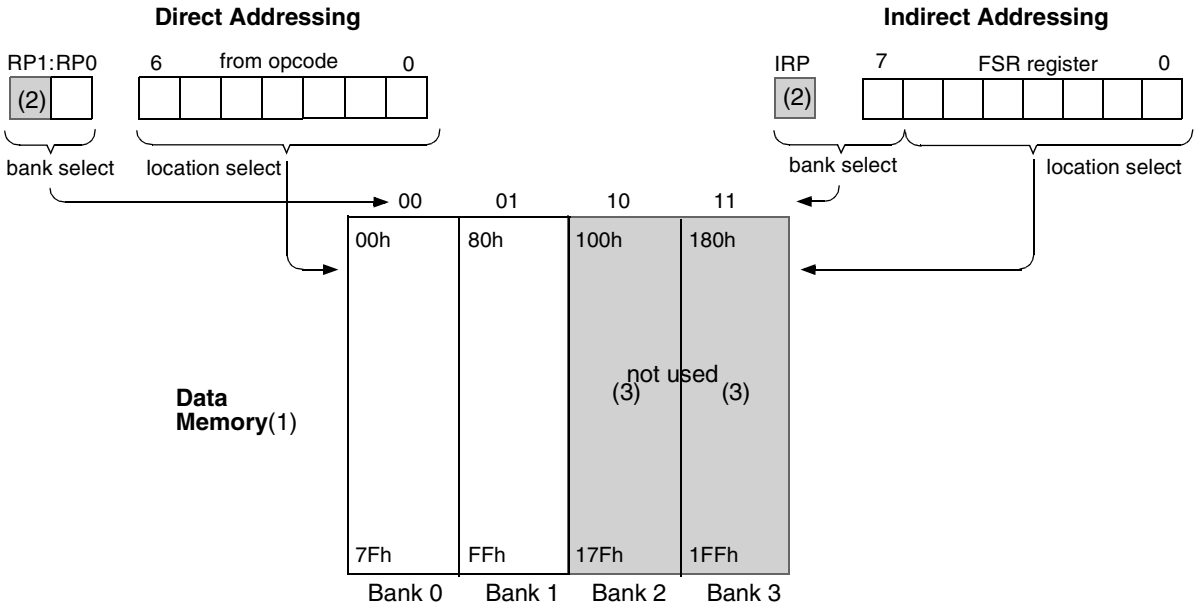
Reading INDF itself indirectly (FSR = 0) will produce 00h. Writing to the INDF register indirectly results in a no-operation (although STATUS bits may be affected).

A simple program to clear RAM locations 20h-2Fh using indirect addressing is shown in Example 2-2.

EXAMPLE 2-2: HOW TO CLEAR RAM USING INDIRECT ADDRESSING

```
          movlw   0x20  ;initialize pointer
          movwf   FSR   ;  to RAM
NEXT      clrf    INDF  ;clear INDF register
          incf    FSR   ;inc pointer
          btfss   FSR,4 ;all done?
          goto    NEXT  ;NO, clear next
CONTINUE
          :             ;YES, continue
```

FIGURE 2-11: DIRECT/INDIRECT ADDRESSING



Note 1: For register file map detail see Figure 2-2.

2: Maintain RP1 and IRP as clear for upward compatibility with future products.

3: Not implemented.

4.2.1 SWITCHING PRESCALER ASSIGNMENT

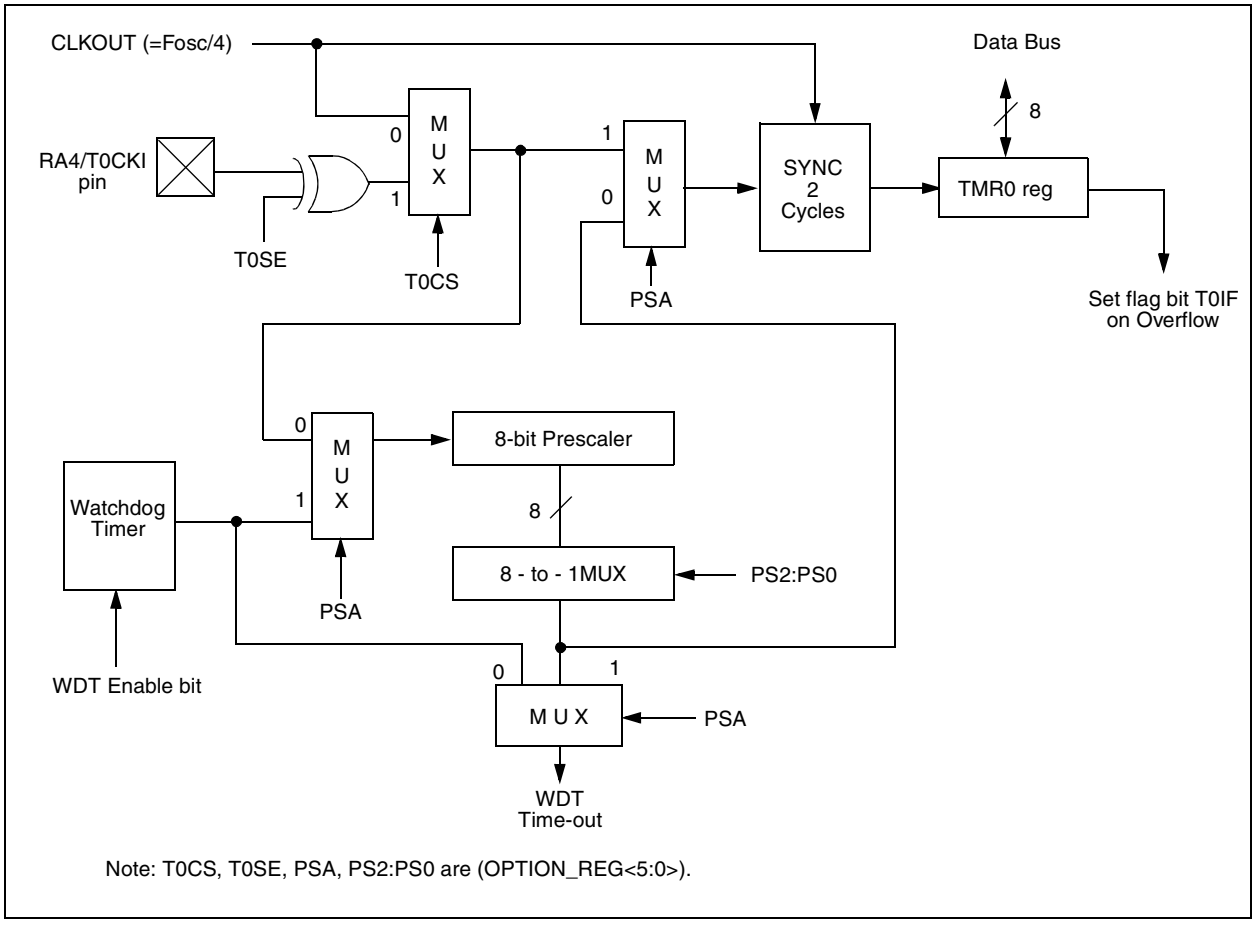
The prescaler assignment is fully under software control, i.e., it can be changed “on the fly” during program execution.

Note:	To avoid an unintended device RESET, a specific instruction sequence (shown in the PIC® Mid-Range MCU Reference Manual, DS3023) must be executed when changing the prescaler assignment from Timer0 to the WDT. This sequence must be followed even if the WDT is disabled.

4.3 Timer0 Interrupt

The TMR0 interrupt is generated when the TMR0 register overflows from FFh to 00h. This overflow sets bit T0IF (INTCON<2>). The interrupt can be masked by clearing bit T0IE (INTCON<5>). Bit T0IF must be cleared in software by the Timer0 module interrupt service routine before re-enabling this interrupt. The TMR0 interrupt cannot awaken the processor from SLEEP since the timer is shut off during SLEEP.

FIGURE 4-2: BLOCK DIAGRAM OF THE TIMER0/WDT PRESCALER



Note: T0CS, T0SE, PSA, PS2:PS0 are (OPTION_REG<5:0>).

TABLE 4-1 REGISTERS ASSOCIATED WITH TIMER0

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR, BOR	Value on all other resets
01h,101h	TMR0	Timer0 module's register								xxxx xxxx	uuuu uuuu
0Bh,8Bh, 10Bh,18Bh	INTCON	GIE	PEIE	T0IE	INTE	RBIE	T0IF	INTF	RBIF	0000 000x	0000 000u
81h,181h	OPTION_REG	$\overline{\text{RBPU}}$	INTEDG	T0CS	T0SE	PSA	PS2	PS1	PS0	1111 1111	1111 1111
85h	TRISA	—	—	PORTA Data Direction Register						--11 1111	--11 1111

Legend: x = unknown, u = unchanged, - = unimplemented locations read as '0'. Shaded cells are not used by Timer0.

6.0 TIMER2 MODULE

The Timer2 module timer has the following features:

- 8-bit timer (TMR2 register)
- 8-bit period register (PR2)
- Readable and writable (Both registers)
- Software programmable prescaler (1:1, 1:4, 1:16)
- Software programmable postscaler (1:1 to 1:16)
- Interrupt on TMR2 match of PR2
- SSP module optional use of TMR2 output to generate clock shift

Timer2 has a control register, shown in Figure 6-2. Timer2 can be shut off by clearing control bit TMR2ON (T2CON<2>) to minimize power consumption.

Figure 6-1 is a simplified block diagram of the Timer2 module.

Additional information on timer modules is available in the PIC® Mid-Range MCU Reference Manual, DS33023.

6.1 Timer2 Operation

Timer2 can be used as the PWM time-base for PWM mode of the CCP module.

The TMR2 register is readable and writable, and is cleared on any device reset.

The input clock (FOSC/4) has a prescale option of 1:1, 1:4 or 1:16, selected by control bits T2CKPS1:T2CKPS0 (T2CON<1:0>).

The match output of TMR2 goes through a 4-bit postscaler (which gives a 1:1 to 1:16 scaling inclusive) to generate a TMR2 interrupt (latched in flag bit TMR2IF, (PIR1<1>)).

The prescaler and postscaler counters are cleared when any of the following occurs:

- a write to the TMR2 register
- a write to the T2CON register
- any device reset (Power-on Reset, $\overline{MCLR}$ reset, Watchdog Timer reset, or Brown-out Reset)

TMR2 is not cleared when T2CON is written.

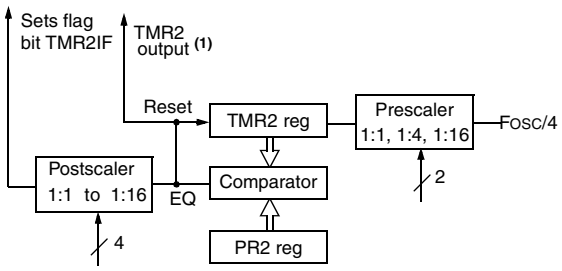
6.2 Timer2 Interrupt

The Timer2 module has an 8-bit period register PR2. Timer2 increments from 00h until it matches PR2 and then resets to 00h on the next increment cycle. PR2 is a readable and writable register. The PR2 register is initialized to FFh upon reset.

6.3 Output of TMR2

The output of TMR2 (before the postscaler) is fed to the Synchronous Serial Port module which optionally uses it to generate shift clock.

FIGURE 6-1: TIMER2 BLOCK DIAGRAM



Note 1: TMR2 register output can be software selected by the SSP Module as a baud clock.

For an example PWM period and duty cycle calculation, see the PIC® Mid-Range MCU Reference Manual (DS33023).

7.3.3 SET-UP FOR PWM OPERATION

The following steps should be taken when configuring the CCP module for PWM operation:

1. Set the PWM period by writing to the PR2 register.
2. Set the PWM duty cycle by writing to the CCPR1L register and CCP1CON<5:4> bits.
3. Make the CCP1 pin an output by clearing the TRISC<2> bit.
4. Set the TMR2 prescale value and enable Timer2 by writing to T2CON.
5. Configure the CCP1 module for PWM operation.

TABLE 7-3 EXAMPLE PWM FREQUENCIES AND RESOLUTIONS AT 20 MHz

PWM Frequency	1.22 kHz	4.88 kHz	19.53 kHz	78.12 kHz	156.3 kHz	208.3 kHz
Timer Prescaler (1, 4, 16)	16	4	1	1	1	1
PR2 Value	0xFF	0xFF	0xFF	0x3F	0x1F	0x17
Maximum Resolution (bits)	10	10	10	8	7	5.5

TABLE 7-4 REGISTERS ASSOCIATED WITH PWM AND TIMER2

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR, BOR	Value on all other resets
0Bh,8Bh	INTCON	GIE	PEIE	T0IE	INTE	RBIE	T0IF	INTF	RBIF	0000 000x	0000 000u
0Ch	PIR1	(1)	ADIF	(1)	(1)	SSPIF	CCP1IF	TMR2IF	TMR1IF	0000 0000	0000 0000
8Ch	PIE1	(1)	ADIE	(1)	(1)	SSPIE	CCP1IE	TMR2IE	TMR1IE	0000 0000	0000 0000
87h	TRISC	PORTC Data Direction Register								1111 1111	1111 1111
11h	TMR2	Timer2 module's register								0000 0000	0000 0000
92h	PR2	Timer2 module's period register								1111 1111	1111 1111
12h	T2CON	—	TOUTPS3	TOUTPS2	TOUTPS1	TOUTPS0	TMR2ON	T2CKPS1	T2CKPS0	-000 0000	-000 0000
15h	CCPR1L	Capture/Compare/PWM register1 (LSB)								xxxx xxxx	uuuu uuuu
16h	CCPR1H	Capture/Compare/PWM register1 (MSB)								xxxx xxxx	uuuu uuuu
17h	CCP1CON	—	—	CCP1X	CCP1Y	CCP1M3	CCP1M2	CCP1M1	CCP1M0	--00 0000	--00 0000

Legend: x = unknown, u = unchanged, - = unimplemented read as '0'. Shaded cells are not used by PWM and Timer2.
Note 1: These bits/registers are unimplemented, read as '0'.

8.2 SPI Mode for PIC16C72

This section contains register definitions and operational characteristics of the SPI module on the PIC16C72 device only.

Additional information on SPI operation may be found in the PIC® Mid-Range MCU Reference Manual, DS33023.

FIGURE 8-1: SSPSTAT: SYNC SERIAL PORT STATUS REGISTER (ADDRESS 94h) (PIC16C72)

U-0	U-0	R-0	R-0	R-0	R-0	R-0	R-0
—	—	D/$\overline{A}$	P	S	R/$\overline{W}$	UA	BF
bit7							bit0

R = Readable bit
W = Writable bit
U = Unimplemented bit, read as '0'
- n =Value at POR reset

bit 7-6: **Unimplemented:** Read as '0'

bit 5: **D/$\overline{A}$**: Data/Address bit (I^2C mode only)
1 = Indicates that the last byte received or transmitted was data
0 = Indicates that the last byte received or transmitted was address

bit 4: **P**: Stop bit (I^2C mode only. This bit is cleared when the SSP module is disabled, SSPEN is cleared)
1 = Indicates that a stop bit has been detected last (this bit is '0' on RESET)
0 = Stop bit was not detected last

bit 3: **S**: Start bit (I^2C mode only. This bit is cleared when the SSP module is disabled, SSPEN is cleared)
1 = Indicates that a start bit has been detected last (this bit is '0' on RESET)
0 = Start bit was not detected last

bit 2: **R/$\overline{W}$**: Read/Write bit information (I^2C mode only)
This bit holds the R/W bit information following the last address match. This bit is valid from the address match to the next start bit, stop bit, or $\overline{ACK}$ bit.
1 = Read
0 = Write

bit 1: **UA**: Update Address (10-bit I^2C mode only)
1 = Indicates that the user needs to update the address in the SSPADD register
0 = Address does not need to be updated

bit 0: **BF**: Buffer Full Status bit

Receive (SPI and I^2C modes)
1 = Receive complete, SSPBUF is full
0 = Receive not complete, SSPBUF is empty

Transmit (I^2C mode only)
1 = Transmit in progress, SSPBUF is full
0 = Transmit complete, SSPBUF is empty

The SPI mode allows 8-bits of data to be synchronously transmitted and received simultaneously. To accomplish communication, typically three pins are used:

- Serial Data Out (SDO) RC5/SDO
- Serial Data In (SDI) RC4/SDI/SDA
- Serial Clock (SCK) RC3/SCK/SCL

Additionally a fourth pin may be used when in a slave mode of operation:

- Slave Select ($\overline{SS}$) RA5/$\overline{SS}$/AN4

When initializing the SPI, several options need to be specified. This is done by programming the appropriate control bits in the SSPCON register (SSPCON<5:0>). These control bits allow the following to be specified:

- Master Operation (SCK is the clock output)
- Slave Mode (SCK is the clock input)
- Clock Polarity (Output/Input data on the Rising/Falling edge of SCK)
- Clock Rate (master operation only)
- Slave Select Mode (Slave mode only)

To enable the serial port, SSP enable bit SSPEN (SSPCON<5>) must be set. To reset or reconfigure SPI mode, clear enable bit SSPEN, re-initialize SSPCON register, and then set enable bit SSPEN. This configures the SDI, SDO, SCK, and $\overline{SS}$ pins as serial port pins. For the pins to behave as the serial port function, they must have their data direction bits (in the TRIS register) appropriately programmed. That is:

- SDI must have TRISC<4> set
- SDO must have TRISC<5> cleared
- SCK (master operation) must have TRISC<3> cleared
- SCK (Slave mode) must have TRISC<3> set
- $\overline{SS}$ must have TRISA<5> set (if implemented)

FIGURE 8-3: SSP BLOCK DIAGRAM (SPI MODE)

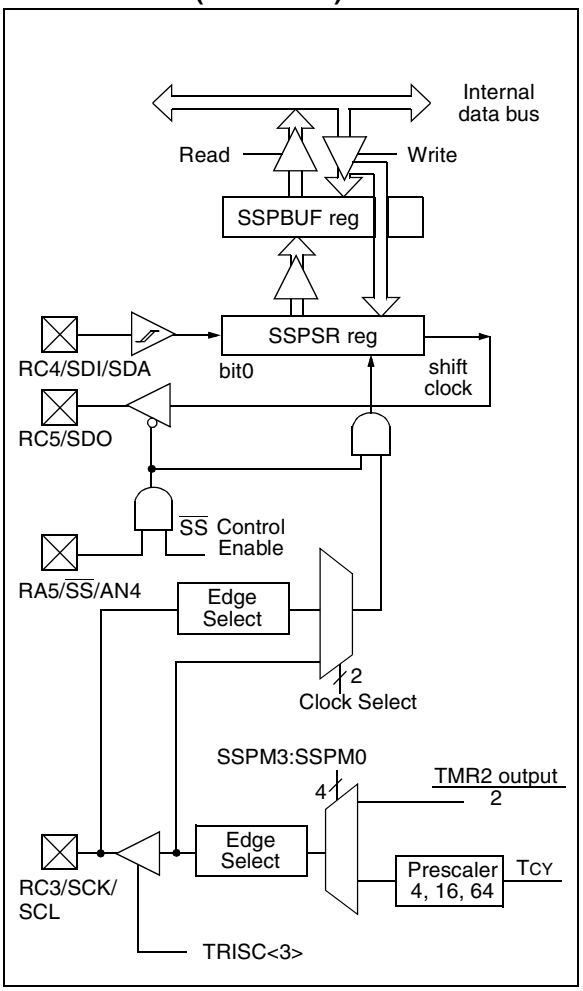


TABLE 8-1 REGISTERS ASSOCIATED WITH SPI OPERATION

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR, BOR	Value on all other resets
0Bh,8Bh	INTCON	GIE	PEIE	T0IE	INTE	RBIE	T0IF	INTF	RBIF	0000 000x	0000 000u
0Ch	PIR1	(1)	ADIF	(1)	(1)	SSPIF	CCP1IF	TMR2IF	TMR1IF	0000 0000	0000 0000
8Ch	PIE1	(1)	ADIE	(1)	(1)	SSPIE	CCP1IE	TMR2IE	TMR1IE	0000 0000	0000 0000
87h	TRISC	PORTC Data Direction Register								1111 1111	1111 1111
13h	SSPBUF	Synchronous Serial Port Receive Buffer/Transmit Register								xxxx xxxx	uuuu uuuu
14h	SSPCON	WCOL	SSPOV	SSPEN	CKP	SSPM3	SSPM2	SSPM1	SSPM0	0000 0000	0000 0000
85h	TRISA	—	—	PORTA Data Direction Register						--11 1111	--11 1111
94h	SSPSTAT	—	—	D/$\overline{A}$	P	S	R/$\overline{W}$	UA	BF	--00 0000	--00 0000

Legend: x = unknown, u = unchanged, - = unimplemented read as '0'. Shaded cells are not used by the SSP in SPI mode.
Note 1: These bits are unimplemented, read as '0'.

8.4.2 MASTER OPERATION

Master operation is supported in firmware using interrupt generation on the detection of the START and STOP conditions. The STOP (P) and START (S) bits are cleared from a reset or when the SSP module is disabled. The STOP (P) and START (S) bits will toggle based on the START and STOP conditions. Control of the I^2C bus may be taken when the P bit is set, or the bus is idle and both the S and P bits are clear.

In master operation, the SCL and SDA lines are manipulated in firmware by clearing the corresponding TRISC<4:3> bit(s). The output level is always low, irrespective of the value(s) in PORTC<4:3>. So when transmitting data, a '1' data bit must have the TRISC<4> bit set (input) and a '0' data bit must have the TRISC<4> bit cleared (output). The same scenario is true for the SCL line with the TRISC<3> bit.

The following events will cause SSP Interrupt Flag bit, SSPIF, to be set (SSP Interrupt if enabled):

- START condition
- STOP condition
- Data transfer byte transmitted/received

Master operation can be done with either the slave mode idle (SSPM3:SSPM0 = 1011) or with the slave active. When both master operation and slave modes are used, the software needs to differentiate the source(s) of the interrupt.

For more information on master operation, see *AN554 - Software Implementation of I^2C Bus Master*.

8.4.3 MULTI-MASTER OPERATION

In multi-master operation, the interrupt generation on the detection of the START and STOP conditions allows the determination of when the bus is free. The STOP (P) and START (S) bits are cleared from a reset or when the SSP module is disabled. The STOP (P) and START (S) bits will toggle based on the START and STOP conditions. Control of the I^2C bus may be taken when bit P (SSPSTAT<4>) is set, or the bus is idle and both the S and P bits clear. When the bus is busy, enabling the SSP Interrupt will generate the interrupt when the STOP condition occurs.

In multi-master operation, the SDA line must be monitored to see if the signal level is the expected output level. This check only needs to be done when a high level is output. If a high level is expected and a low level is present, the device needs to release the SDA and SCL lines (set TRISC<4:3>). There are two stages where this arbitration can be lost, these are:

- Address Transfer
- Data Transfer

When the slave logic is enabled, the slave continues to receive. If arbitration was lost during the address transfer stage, communication to the device may be in progress. If addressed an $\overline{ACK}$ pulse will be generated. If arbitration was lost during the data transfer stage, the device will need to re-transfer the data at a later time.

For more information on master operation, see *AN578 - Use of the SSP Module in the of I^2C Multi-Master Environment*.

TABLE 8-4 REGISTERS ASSOCIATED WITH I^2C OPERATION

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR	Value on all other resets
0Bh, 8Bh, 10Bh,18Bh	INTCON	GIE	PEIE	T0IE	INTE	RBIE	T0IF	INTF	RBIF	0000 000x	0000 000u
0Ch	PIR1	(1)	ADIF	(1)	(1)	SSPIF	CCP1IF	TMR2IF	TMR1IF	0000 0000	0000 0000
8Ch	PIE1	(1)	ADIE	(1)	(1)	SSPIE	CCP1IE	TMR2IE	TMR1IE	0000 0000	0000 0000
13h	SSPBUF	Synchronous Serial Port Receive Buffer/Transmit Register								xxxx xxxx	uuuu uuuu
93h	SSPADD	Synchronous Serial Port (I^2C mode) Address Register								0000 0000	0000 0000
14h	SSPCON	WCOL	SSPOV	SSPEN	CKP	SSPM3	SSPM2	SSPM1	SSPM0	0000 0000	0000 0000
94h	SSPSTAT	SMP(2)	CKE(2)	D/$\overline{A}$	P	S	R/$\overline{W}$	UA	BF	0000 0000	0000 0000
87h	TRISC	PORTC Data Direction register								1111 1111	1111 1111

Legend: x = unknown, u = unchanged, - = unimplemented locations read as '0'.
Shaded cells are not used by SSP module in SPI mode.

Note 1: These bits are unimplemented, read as '0'.
2: The SMP and CKE bits are implemented on the PIC16CR72 only. On the PIC16C72, these two bits are unimplemented, read as '0'.

NOTES:

13.1 DC Characteristics: PIC16C72/CR72-04 (Commercial, Industrial, Extended) PIC16C72/CR72-10 (Commercial, Industrial, Extended) PIC16C72/CR72-20 (Commercial, Industrial, Extended)

DC CHARACTERISTICS	Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +125°C for extended, -40°C ≤ TA ≤ +85°C for industrial and 0°C ≤ TA ≤ +70°C for commercial

Param No.	Characteristic	Sym	PIC16C72			PIC16CR72			Units	Conditions
			Min	Typ†	Max	Min	Typ†	Max		
D001	Supply Voltage	VDD	4.0	-	**6.0**	4.0	-	**5.5**	V	XT, RC and LP osc
D001A			4.5	-	5.5	4.5	-	5.5	V	HS osc
D002*	RAM Data Retention Voltage (Note 1)	VDR	-	1.5	-	-	1.5	-	V	
D003	VDD start voltage to ensure internal Power-on Reset Signal	VPOR	-	VSS	-	-	VSS	-	V	See section on Power-on Reset for details
D004*	VDD rise rate to ensure internal Power-on Reset Signal	SVDD	0.05	-	-	0.05	-	-	V/ms	See section on Power-on Reset for details
D005	Brown-out Reset Voltage	Bvdd	3.7	4.0	4.3	3.7	4.0	4.3	V	BODEN bit in configuration word enabled
			3.7	4.0	4.4	3.7	4.0	4.4	V	Extended Only
D010	Supply Current (Note 2,5)	IDD	-	2.7	5.0	-	2.7	5.0	mA	XT, RC osc FOSC = 4 MHz, VDD = 5.5V (Note 4)
D013			-	10	20	-	10	20	mA	HS osc FOSC = 20 MHz, VDD = 5.5V
D015	Brown-out Reset Current (Note 6)	ΔIbor	-	350	425	-	350	425	µA	BOR enabled, VDD = 5.0V
D020	Power-down Current (Note 3,5)	IPD	-	10.5	42	-	10.5	42	µA	VDD = 4.0V, WDT enabled, -40°C to +85°C
D021			-	1.5	16	-	1.5	16	µA	VDD = 4.0V, WDT disabled, -0°C to +70°C
D021A			-	1.5	19	-	1.5	19	µA	VDD = 4.0V, WDT disabled, -40°C to +85°C
D021B			-	2.5	19	-	2.5	19	µA	VDD = 4.0V, WDT disabled, -40°C to +125°C
D023	Brown-out Reset Current (Note 6)	ΔIbor	-	350	425	-	350	425	µA	BOR enabled VDD = 5.0V

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: This is the limit to which VDD can be lowered without losing RAM data.

Note 2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as I/O pin loading and switching rate, oscillator type, internal code execution pattern, and temperature also have an impact on the current consumption.

The test conditions for all IDD measurements in active operation mode are:
OSC1 = external square wave, from rail to rail; all I/O pins tristated, pulled to VDD
$\overline{MCLR}$ = VDD; WDT enabled/disabled as specified.

Note 3: The power-down current in SLEEP mode does not depend on the oscillator type. Power-down current is measured with the part in SLEEP mode, with all I/O pins in hi-impedance state and tied to VDD and VSS.

Note 4: For RC osc configuration, current through Rext is not included. The current through the resistor can be estimated by the formula Ir = VDD/2Rext (mA) with Rext in kOhm.

Note 5: Timer1 oscillator (when enabled) adds approximately 20 µA to the specification. This value is from characterization and is for design guidance only. This is not tested.

Note 6: The Δ current is the additional current consumed when this peripheral is enabled. This current should be added to the base IDD or IPD measurement.

13.3 DC Characteristics: PIC16C72/CR72-04 (Commercial, Industrial, Extended) PIC16C72/CR72-10 (Commercial, Industrial, Extended) PIC16C72/CR72-20 (Commercial, Industrial, Extended) PIC16LC72/LCR72-04 (Commercial, Industrial)

DC CHARACTERISTICS			Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +125°C for extended, -40°C ≤ TA ≤ +85°C for industrial and 0°C ≤ TA ≤ +70°C for commercial Operating voltage VDD range as described in DC spec Section 13.1 and Section 13.2.				
Param No.	**Characteristic**	**Sym**	**Min**	**Typ†**	**Max**	**Units**	**Conditions**
	Input Low Voltage						
	I/O ports	VIL					
D030	with TTL buffer		VSS	-	0.15VDD	V	For entire VDD range
D030A			Vss	-	0.8V	V	4.5 ≤ VDD ≤ 5.5V
D031	with Schmitt Trigger buffer		VSS	-	0.2VDD	V	
D032	$\overline{MCLR}$, OSC1 (in RC mode)		VSS	-	0.2VDD	V	
D033	OSC1 (in XT, HS and LP)		VSS	-	0.3VDD	V	Note1
	Input High Voltage						
	I/O ports	VIH		-			
D040	with TTL buffer		2.0	-	VDD	V	4.5 ≤ VDD ≤ 5.5V
D040A			0.25VDD + 0.8V	-	VDD	V	For entire VDD range
D041	with Schmitt Trigger buffer		0.8VDD	-	VDD	V	For entire VDD range
D042	MCLR		0.8VDD	-	VDD	V	
D042A	OSC1 (XT, HS and LP)		0.7VDD	-	Vdd	V	Note1
D043	OSC1 (in RC mode)		0.9VDD	-	VDD	V	
D070	**PORTB weak pull-up current**	IPURB	50	250	†400	µA	VDD = 5V, VPIN = VSS
	Input Leakage Current (Notes 2, 3)						
D060	I/O ports	IIL	-	-	±1	µA	Vss ≤ VPIN ≤ VDD, Pin at hi-impedance
D061	$\overline{MCLR}$, RA4/T0CKI		-	-	±5	µA	Vss ≤ VPIN ≤ VDD
D063	OSC1		-	-	±5	µA	Vss ≤ VPIN ≤ VDD, XT, HS and LP osc configuration
	Output Low Voltage						
D080	I/O ports	VOL	-	-	0.6	V	IOL = 8.5 mA, VDD = 4.5V, -40°C to +85°C
D080A			-	-	0.6	V	IOL = 7.0 mA, VDD = 4.5V, -40°C to +125°C
D083	OSC2/CLKOUT (RC osc config)		-	-	0.6	V	IOL = 1.6 mA, VDD = 4.5V, -40°C to +85°C
D083A			-	-	0.6	V	IOL = 1.2 mA, VDD = 4.5V, -40°C to +125°C

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: In RC oscillator configuration, the OSC1/CLKIN pin is a Schmitt trigger input. It is not recommended that the PIC16C7X be driven with external clock in RC mode.

Note 2: The leakage current on the $\overline{MCLR}$/VPP pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

Note 3: Negative current is defined as current sourced by the pin.

13.5 Timing Diagrams and Specifications

FIGURE 13-2: EXTERNAL CLOCK TIMING

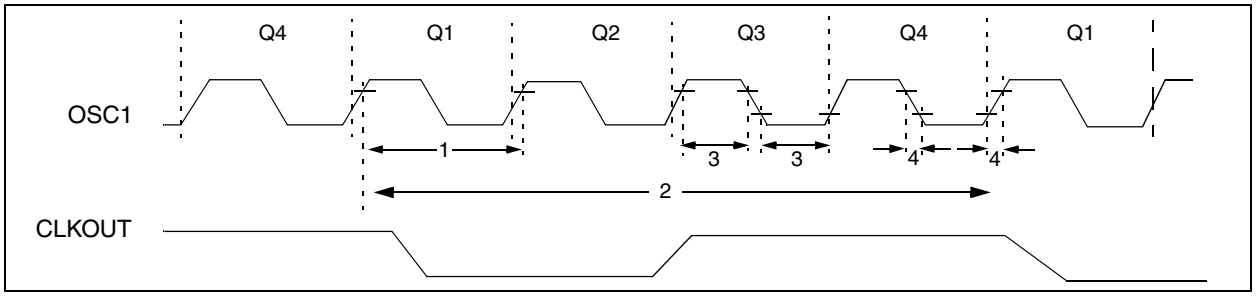


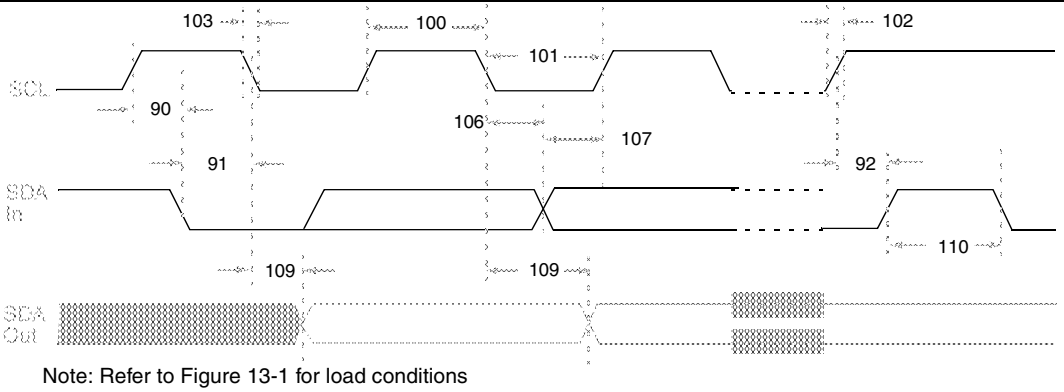
TABLE 13-3 EXTERNAL CLOCK TIMING REQUIREMENTS

Parameter No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
	Fosc	External CLKIN Frequency (Note 1)	DC	—	4	MHz	XT and RC osc mode
			DC	—	4	MHz	HS osc mode (-04)
			DC	—	10	MHz	HS osc mode (-10)
			DC	—	20	MHz	HS osc mode (-20)
			DC	—	200	kHz	LP osc mode
		Oscillator Frequency (Note 1)	DC	—	4	MHz	RC osc mode
			0.1	—	4	MHz	XT osc mode
			4	—	20	MHz	HS osc mode
			5	—	200	kHz	LP osc mode
1	Tosc	External CLKIN Period (Note 1)	250	—	—	ns	XT and RC osc mode
			250	—	—	ns	HS osc mode (-04)
			100	—	—	ns	HS osc mode (-10)
			50	—	—	ns	HS osc mode (-20)
			5	—	—	µs	LP osc mode
		Oscillator Period (Note 1)	250	—	—	ns	RC osc mode
			250	—	10,000	ns	XT osc mode
			250	—	250	ns	HS osc mode (-04)
			100	—	250	ns	HS osc mode (-10)
			50	—	250	ns	HS osc mode (-20)
			5	—	—	µs	LP osc mode
2	TCY	Instruction Cycle Time (Note 1)	200	—	DC	ns	TCY = 4/FOSC
3	TosL, TosH	External Clock in (OSC1) High or Low Time	100	—	—	ns	XT oscillator
			2.5	—	—	µs	LP oscillator
			15	—	—	ns	HS oscillator
4	TosR, TosF	External Clock in (OSC1) Rise or Fall Time	—	—	25	ns	XT oscillator
			—	—	50	ns	LP oscillator
			—	—	15	ns	HS oscillator

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: Instruction cycle period (TCY) equals four times the input oscillator time-base period. All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption. All devices are tested to operate at "min." values with an external clock applied to the OSC1/CLKIN pin. When an external clock input is used, the "Max." cycle time limit is "DC" (no clock) for all devices.

FIGURE 13-13: I²C BUS DATA TIMING



Note: Refer to Figure 13-1 for load conditions

TABLE 13-11 I²C BUS DATA REQUIREMENTS

Parameter No.	Sym	Characteristic		Min	Max	Units	Conditions
100	THIGH	Clock high time	100 kHz mode	4.0	—	µs	Device must operate at a minimum of 1.5 MHz
			400 kHz mode	0.6	—	µs	Device must operate at a minimum of 10 MHz
			SSP Module	1.5TCY	—		
101	TLOW	Clock low time	100 kHz mode	4.7	—	µs	Device must operate at a minimum of 1.5 MHz
			400 kHz mode	1.3	—	µs	Device must operate at a minimum of 10 MHz
			SSP Module	1.5TCY	—		
102	TR	SDA and SCL rise time	100 kHz mode	—	1000	ns	
			400 kHz mode	20 + 0.1Cb	300	ns	Cb is specified to be from 10 to 400 pF
103	TF	SDA and SCL fall time	100 kHz mode	—	300	ns	
			400 kHz mode	20 + 0.1Cb	300	ns	Cb is specified to be from 10 to 400 pF
90	TSU:STA	START condition setup time	100 kHz mode	4.7	—	µs	Only relevant for repeated START condition
			400 kHz mode	0.6	—	µs	
91	THD:STA	START condition hold time	100 kHz mode	4.0	—	µs	After this period the first clock pulse is generated
			400 kHz mode	0.6	—	µs	
106	THD:DAT	Data input hold time	100 kHz mode	0	—	ns	
			400 kHz mode	0	0.9	µs	
107	TSU:DAT	Data input setup time	100 kHz mode	250	—	ns	Note 2
			400 kHz mode	100	—	ns	
92	TSU:STO	STOP condition setup time	100 kHz mode	4.7	—	µs	
			400 kHz mode	0.6	—	µs	
109	TAA	Output valid from clock	100 kHz mode	—	3500	ns	Note 1
			400 kHz mode	—	—	ns	
110	TBUF	Bus free time	100 kHz mode	4.7	—	µs	Time the bus must be free before a new transmission can start
			400 kHz mode	1.3	—	µs	
	Cb	Bus capacitive loading		—	400	pF	

Note 1: As a transmitter, the device must provide this internal minimum delay time to bridge the undefined region (min. 300 ns) of the falling edge of SCL to avoid unintended generation of START or STOP conditions.

Note 2: A fast-mode (400 kHz) I²C-bus device can be used in a standard-mode (100 kHz)S I²C-bus system, but the requirement tsu;DAT ≥ 250 ns must then be met. This will automatically be the case if the device does not stretch the LOW period of the SCL signal. If such a device does stretch the LOW period of the SCL signal, it must output the next data bit to the SDA line TR max.+tsu;DAT = 1000 + 250 = 1250 ns (according to the standard-mode I²C bus specification) before the SCL line is released.

NOTES:

FIGURE 14-18: TYPICAL IDD vs. CAPACITANCE @ 500 kHz (RC MODE)

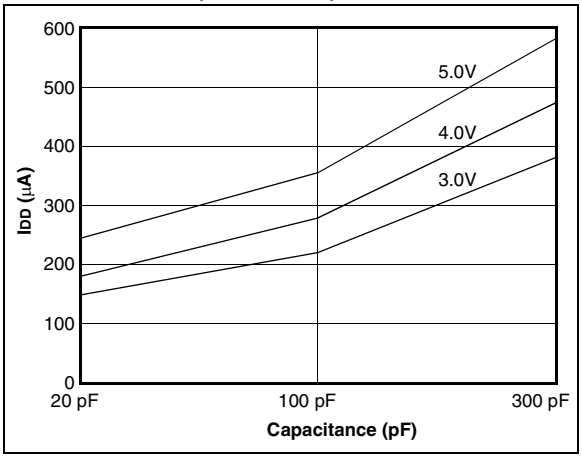


TABLE 14-1 RC OSCILLATOR FREQUENCIES

Cext	Rext	Average Fosc @ 5V, 25°C	
22 pF	5k	4.12 MHz	± 1.4%
	10k	2.35 MHz	± 1.4%
	100k	268 kHz	± 1.1%
100 pF	3.3k	1.80 MHz	± 1.0%
	5k	1.27 MHz	± 1.0%
	10k	688 kHz	± 1.2%
	100k	77.2 kHz	± 1.0%
300 pF	3.3k	707 kHz	± 1.4%
	5k	501 kHz	± 1.2%
	10k	269 kHz	± 1.6%
	100k	28.3 kHz	± 1.1%

The percentage variation indicated here is part to part variation due to normal process distribution. The variation indicated is ±3 standard deviation from average value for VDD = 5V.

FIGURE 14-19: TRANSCONDUCTANCE(gm) OF HS OSCILLATOR vs. VDD

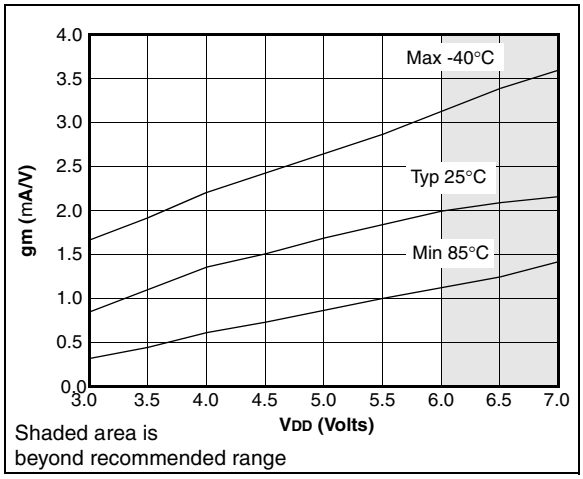


FIGURE 14-20: TRANSCONDUCTANCE(gm) OF LP OSCILLATOR vs. VDD

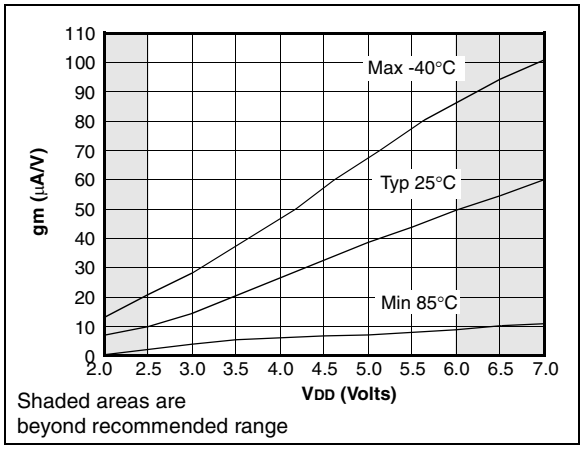
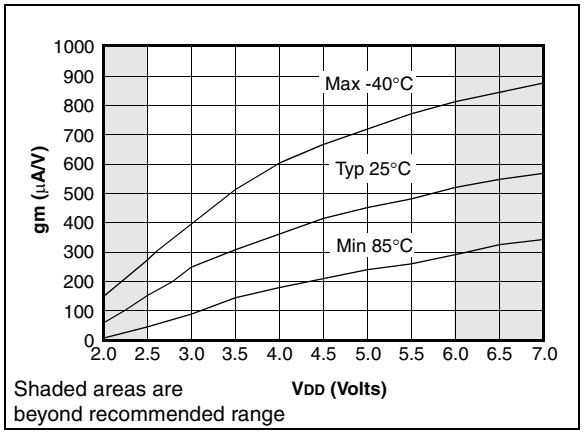


FIGURE 14-21: TRANSCONDUCTANCE(gm) OF XT OSCILLATOR vs. VDD



Data based on matrix samples. See first page of this section for details.

FIGURE 14-22: TYPICAL XTAL STARTUP TIME vs. VDD (LP MODE, 25°C)

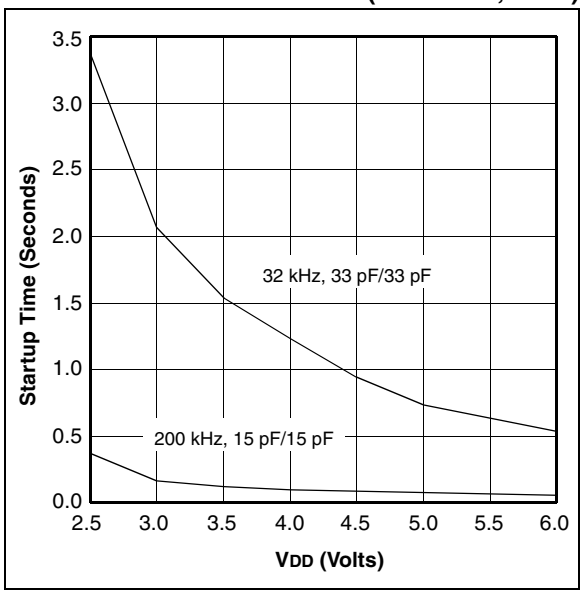


FIGURE 14-23: TYPICAL XTAL STARTUP TIME vs. VDD (HS MODE, 25°C)

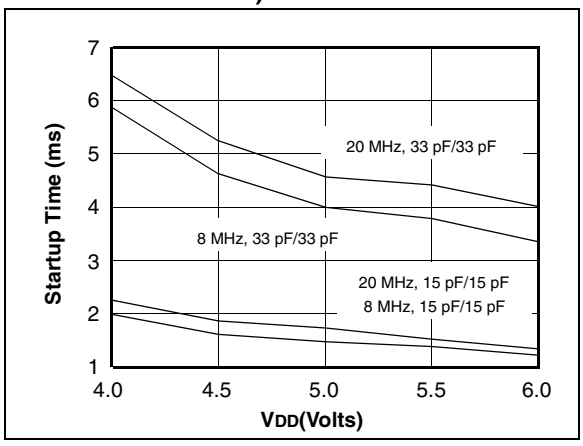


FIGURE 14-24: TYPICAL XTAL STARTUP TIME vs. VDD (XT MODE, 25°C)

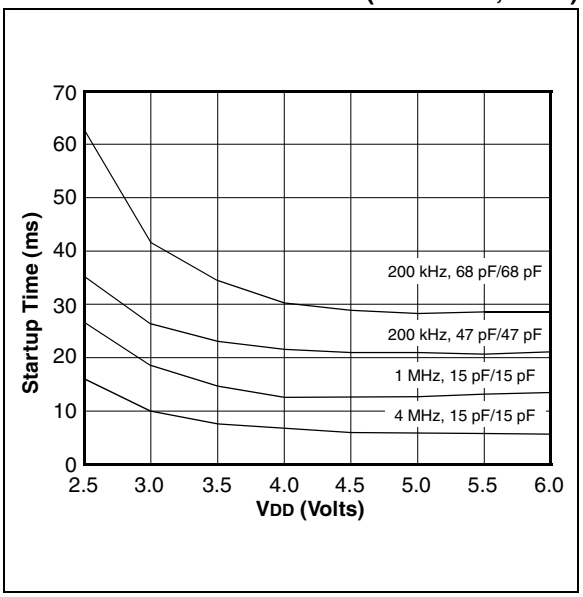


TABLE 14-2 CAPACITOR SELECTION FOR CRYSTAL OSCILLATORS

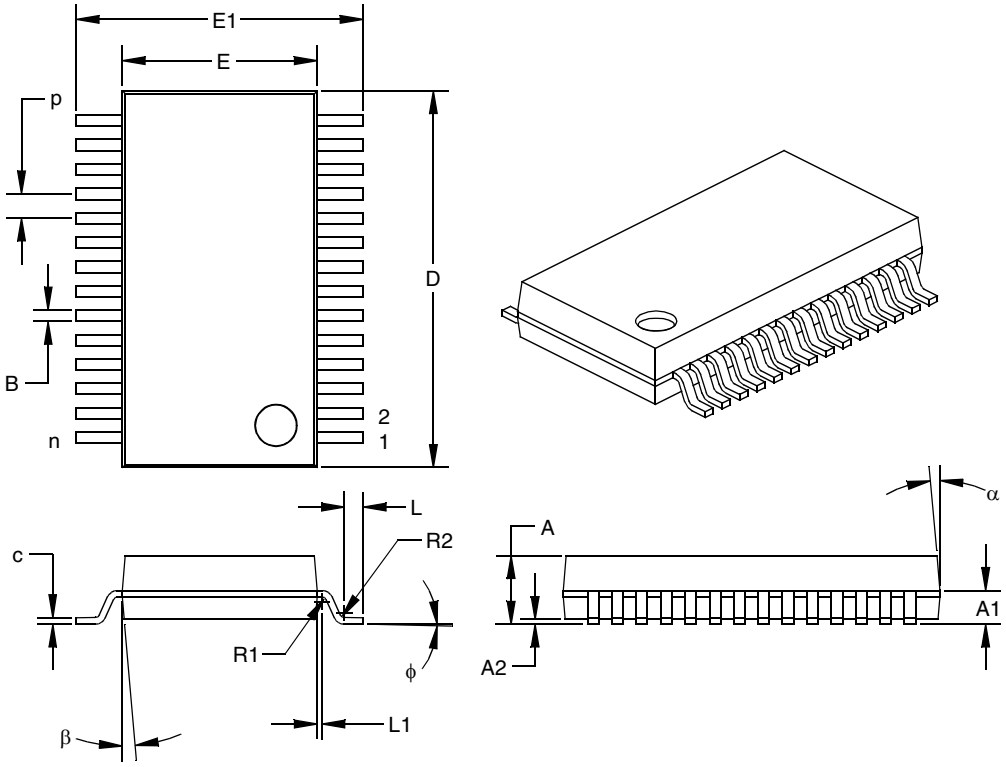
Osc Type	Crystal Freq	Cap. Range C1	Cap. Range C2
LP	32 kHz	33 pF	33 pF
	200 kHz	15 pF	15 pF
XT	200 kHz	47-68 pF	47-68 pF
	1 MHz	15 pF	15 pF
	4 MHz	15 pF	15 pF
HS	4 MHz	15 pF	15 pF
	8 MHz	15-33 pF	15-33 pF
	20 MHz	15-33 pF	15-33 pF
Crystals Used			
32 kHz	Epson C-001R32.768K-A	± 20 PPM	
200 kHz	STD XTL 200.000KHz	± 20 PPM	
1 MHz	ECS ECS-10-13-1	± 50 PPM	
4 MHz	ECS ECS-40-20-1	± 50 PPM	
8 MHz	EPSON CA-301 8.000M-C	± 30 PPM	
20 MHz	EPSON CA-301 20.000M-C	± 30 PPM	

Data based on matrix samples. See first page of this section for details.

NOTES:

16.5 28-Lead Plastic Surface Mount (SSOP - 209 mil Body 5.30 mm) (SS)

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		INCHES			MILLIMETERS*		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Pitch	p		0.026			0.65	
Number of Pins	n		28			28	
Overall Pack. Height	A	0.068	0.073	0.078	1.73	1.86	1.99
Shoulder Height	A1	0.026	0.036	0.046	0.66	0.91	1.17
Standoff	A2	0.002	0.005	0.008	0.05	0.13	0.21
Molded Package Length	D‡	0.396	0.402	0.407	10.07	10.20	10.33
Molded Package Width	E‡	0.205	0.208	0.212	5.20	5.29	5.38
Outside Dimension	E1	0.301	0.306	0.311	7.65	7.78	7.90
Shoulder Radius	R1	0.005	0.005	0.010	0.13	0.13	0.25
Gull Wing Radius	R2	0.005	0.005	0.010	0.13	0.13	0.25
Foot Length	L	0.015	0.020	0.025	0.38	0.51	0.64
Foot Angle	ϕ	0	4	8	0	4	8
Radius Centerline	L1	0.000	0.005	0.010	0.00	0.13	0.25
Lead Thickness	c	0.005	0.007	0.009	0.13	0.18	0.22
Lower Lead Width	B†	0.010	0.012	0.015	0.25	0.32	0.38
Mold Draft Angle Top	α	0	5	10	0	5	10
Mold Draft Angle Bottom	β	0	5	10	0	5	10

* Controlling Parameter.

† Dimension “B” does not include dam-bar protrusions. Dam-bar protrusions shall not exceed 0.003” (0.076 mm) per side or 0.006” (0.152 mm) more than dimension “B.”

‡ Dimensions “D” and “E” do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.010” (0.254 mm) per side or 0.020” (0.508 mm) more than dimensions “D” or “E.”